

ABSTRACT

A wafer pre-alignment device is disclosed, including a first unit (40) configured to drive a wafer (60) to rotate or move upward or downward, a second unit (50) configured to drive the wafer to translate, and a position detector including a light source, a lens and an image sensor (20). A light beam from the light source passes through the wafer and the lens and thereby provides information indicating a position of the wafer to the image sensor. The first unit and the second unit are able to adjust the position of the wafer based on the information obtained by the image sensor. A method for pre-aligning a TSV wafer is also disclosed.